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# FSA8108 Audio Jack Detection Solution Featuring Volume Up/Down & Send/End Detection

#### Features

- Detection:
  - Accessory Plug-In
  - Send / End Key Press
  - Volume Up/Down Key Press
- V<sub>DD</sub> 2.7 to 4.5 V
- V<sub>IO</sub> 1.6 V to V<sub>DD</sub>
- THD (MIC) 0.01% Typical
- LDO Output for MIC Bias Voltage: 2.4 V
- ESD (IEC 61000-4-2) 15 kV Air Gap
- Detects 3- or 4-Pole Audio Accessories
- Removes Audio Jack Pop-and-Click Caused by MIC Bias

#### Applications

- Cellular Phones, Smart Phones
- MP3 and PMP (Portable Media Player)

#### Description

The FSA8108 is an audio jack detection switch for 3- or 4pole accessories that detects the audio plug connection. The FSA8108 detects volume up/down or send/end key presses. An LDO provides DC bias to microphone and remote key circuit in the accessory. For system flexibility, the FSA8108 features an  $I^2C$  port with registers to allow programmability of AC timing specifications.



#### **Ordering Information**

Part Number	Operating Temperature Range	Top Mark	Package
FSA8108BUCX <sup>(1)</sup>	-40 to +85°C	G6	12-Ball, 3 x 4 Array, 0.4 mm Pitch, 250 μm Ball, Wafer-Level Chip-Scale Package

#### Note:

1. Includes backside lamination.

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#### Notes:

- A 1 kΩ resistor with a 2.2 µF capacitor is recommended for direct battery connection. This filter helps stabilize power rail events not associated with the FSA8039A. If power is supplied from a stable source, such as from a PMIC or LDO, a single 1 µF capacitor is recommended.
- The J-DET is shorted to the left (L) audio channel when the headset or accessory plug is inserted into most audio jacks. Any external circuitry attached to the J-DET pin could affect audio performance in the 20-20 kHz range on the left channel.
- 4. The optional 10 k $\Omega$  resistor on the left channel is used to assist in detection of high-impedance accessories. This resistor has negligible impact on audio fidelity.



### **Pin Definitions**

	r								
Name	PIN	Туре	Description						
INTB	A1	Output	Interrupt. Low is interrupt asserted.						
SDA	B1	Data	I <sup>2</sup> C data						
SCL	C1	Data	I <sup>2</sup> C input clock						
CAP	D1	Output	Internal LDO output. A capacitor to ground is required.						
VIO	A2	Power	Baseband I/O supply voltage						
RES	B2	Input	Device reset control. Active high reset. Connect to GND if unused.						
GND	C2	GND	Ground						
V_MIC	D2	Power	LDO output to supply MIC bias voltage (2.4 V)						
VDD	A3	Power	Core supply voltage						
J_DET	B3	I/O	Input from a pin of the audio jack socket; plug insert/removal detection pin.						
J_MIC	C3	I/O	Microphone switch path that connects to the audio jack.						
MIC	D3	I/O	Microphone switch path that goes to the microphone input of the codec.						

#### **Application Information**

#### **Music Mode**

When a 4-pole headset is inserted into the audio jack and a music/listening application is used, the MIC bias is normally enabled for headset button press detection (i.e. mute, volume change, etc.). This consumes power due to a constant path from the MIC bias resistor and microphone in the headset to GND. Fairchild has developed a Music Mode to enable the MIC switch periodically to monitor for a pressed button. This results in a power savings for battery-sensitive devices, such as cell phones or MP3 players. The FSA8108 enters Music Mode when the Music Mode Enable bit in CONTROL(0Ch) is set and a plug is inserted,. Music Mode reduces MIC bias current by approximately 80% with the default Music Mode timing (09h) register value.

#### LDO Operation

The integrated microphone bias LDO is set to 2.4 V. The LDO can be used to bias a microphone accessory and is enabled / disabled by the I<sup>2</sup>C register bit LDO ENABLE in the CONTROL register(0Ch). This LDO requires a 0.22  $\mu F$  decoupling capacitor on the output. The decoupling capacitor should be placed close to the LDO pin.

#### **Headset Key-Press Operation**

The headset key-press comparator threshold is a function of the MIC bias voltage, MIC bias resistor, and the MIC impedance. All of these variables must be considered when calculating the key-press resistor value. 0 is an example of how to calculate the key-press resistor value.



#### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
$V_{DD,} V_{IO}$	Supply Voltage from Battery		-0.5	6.0	V
V <sub>SW</sub>	Switch I/O Voltage		-0.5	V <sub>CC</sub> +0.5	V
I <sub>V_MIC</sub>	V_MIC LDO Supply Current			15	mA
Іік	Input Clamp Diode Current		-50		mA
I <sub>SW</sub>	Switch I/O Current			50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Maximum Junction Temperature		+150	°C	
TL	Lead Temperature (Soldering, 10 Seconds)			+260	°C
		Air Gap		15	
	IEC 61000-4-2 System ESD	Contact		8	
ESD	Human Body Model, JEDEC JESD22-A114	J_DET vs. GND, J_MIC vs. GND, VDD vs. GND, VIO vs. GND		11	kV
		All Pins		4	
	Charged Device Model, JEDEC JESD22-C101	All Pins		2	

#### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>DD</sub>	Supply Voltage	2.7	4.5	V
V <sub>IO</sub>	I/O Supply Voltage	1.6	V <sub>DD</sub>	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C
V <sub>IN</sub>	MIC Switch Input Voltage Range	0	V <sub>DD</sub>	V
V <sub>Audio</sub>	Audio Voltage Range on J_DET Pin	-1	1	V
f <sub>Audio</sub>	Audio Frequency on J_DET Pin	20	20000	Hz
J_DET <sub>RL</sub>	Resistance on Audio Accessory Left Channel to generate Attach		500	kΩ

All typical values are at  $T_{\text{A}}{=}25^{\circ}\text{C}$  unless otherwise specified.

Ourseland	Deservation		Condition	T <sub>A</sub> =-	35°C	Unit	
Symbol	Parameter	V <sub>DD</sub> (V)	Condition	Min.	Тур.	Max.	Unit
MIC Switch						•	
R <sub>ON</sub>	MIC Switch On Resistance	3.8	I <sub>OUT</sub> =24 mA, V <sub>IN</sub> =2.0 V		0.8	2.5	Ω
R <sub>FLAT</sub>	On Resistance Flatness	3.8	$I_{OUT}$ =24 mA, V <sub>IN</sub> =1 V to V <sub>DD</sub>		0.7		Ω
$C_{\text{ON(MIC)}}$	MIC Switch On Capacitance	3.8	f=1 MHz, $V_{IN}$ =100 mV, 50 mV <sub>PP</sub>		16		pF
$C_{OFF(MIC)}$	MIC Switch Off Capacitance	3.8	f=1 MHz, V <sub>IN</sub> =100 mV, 50 mV <sub>PP</sub>		30		pF
J-DET							
J_DET <sub>HYS</sub>	Hysteresis of J_DET				200		mV
Parallel I/O	Control Signals						
VIL	Low-Level Input Voltage					0.3 • V <sub>IO</sub>	V
VIH	High-Level Input Voltage			0.7 • V <sub>IO</sub>		VIO	V
I <sup>2</sup> C Control	er DC Characteristics Fast Mode (40	0 kHz)					
VIL	Low-Level Input Voltage			-0.5		0.3 V <sub>IO</sub>	V
V <sub>IH</sub>	High-Level Input Voltage			0.7 V <sub>IO</sub>			V
Vinc	Hysteresis of Schmitt Trigger Inputs		V <sub>IO</sub> >2 V			$0.05\;V_{\text{IO}}$	v
• 113			V <sub>IO</sub> <2 V			0.1 V <sub>IO</sub>	, ,
Vol 1	Output Voltage (Open-Drain)		V <sub>IO</sub> >2 V, 3 mA	0		0.4	V
			V <sub>IO</sub> <2 V, 3 mA			0.2 V <sub>IO</sub>	V
I <sub>I2C</sub>	Input Current of SDA and SCL Pins, Input Voltage 0.26 V to 2.34 V			-10		10	μA
Cı	Capacitance for Each I/O Pin <sup>(5)</sup>					10	pF
Current Co	nsumption			de la compañía de la			
I <sub>OZ</sub>	Off Leakage Current	4.5	MIC and J_MIC Port $V_{IN} = 4.4 V$			1.5	μA
I <sub>IN</sub>	Input Leakage Current	0 to 4.5	Inputs 0 to 4.4 V		1		μA
I <sub>DD-SLNA</sub>	Sleep Mode Current with No Accessory	2.7 to 4.5	J_DET=1		1.5		μA
I <sub>DD-SLWA</sub>	Current After Detection With Accessory (Normal Mode)	2.7 to 4.5	J_DET=0		35		μA
I <sub>DD-</sub> MUSIC_MODE	Music Mode	2.7 to 4.5	I <sup>2</sup> C Default Settings		25	$\sim$	μA
I <sub>DD_LDO</sub>	Current to Operating LDO, Not Including Output Current	2.7 to 4.5	LDO Powered		110	$\sim$	μA
I <sub>DD</sub> -SLWA + LDO	Current After Detection With Accessory (Normal Mode) with LDO Current	2.7 to 4.5	J_DET=0		145		μA
I <sub>DD_Music Mode</sub> + LDO	Music Mode with LDO	2.7 to 4.5	I <sup>2</sup> C Default Settings		135		μA

Continued on the following page...

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# **DC Electrical Characteristics**

All typical values are at  $T_A=25^{\circ}C$  unless otherwise specified.

Symbol	Deremeter		Condition	T <sub>A</sub> =-40 to +85°C			Unit	
Symbol	Parameter	V <sub>DD</sub> (V)	Condition	Min.	Тур.	Max.	Unit	
MIC_V LDO	Outputs							
MIC_V <sub>VOUT</sub>	Output Voltage	2.7 to 4.5		-5%	2.4	+5%	V	
$MIC\_V_{IOUT}$	Maximum Output Current	2.7 to 4.5		10			mA	
Comparator Thresholds for Headset Key Pad (Default Voltage Reference)								
V <sub>COMP1</sub>	Comparator Threshold for Send/End Sensing for NO Headset	2.7 to 4.5	I <sup>2</sup> C Default Setting, V <sub>MIC</sub> =2.4 V, R <sub>MIC</sub> =2.2 kΩ	-12%	120	+12%	mV	
V <sub>COMP2</sub>	Comparator Threshold for Send/End Sensing for NC Headset	2.7 to 4.5	I <sup>2</sup> C Default Setting, V <sub>MIC</sub> =2.4 V, R <sub>MIC</sub> =2.2 kΩ	-5%	2300	+5%	mV	
V <sub>COMP3</sub>	Comparator Threshold for Volume_Up Sensing	2.7 to 4.5	I <sup>2</sup> C Default Setting, V <sub>MIC</sub> =2.4 V, R <sub>MIC</sub> =2.2 kΩ	-7%	250	+7%	mV	
V <sub>COMP4</sub>	Comparator Threshold for Volume_Down Sensing	2.7 to 4.5	$I^2C$ Default Setting, $V_{MIC}{=}2.4$ V, $R_{MIC}{=}2.2$ k $\Omega$	-7%	690	+7%	mV	

Note:

5. Not production tested.

# **AC Electrical Characteristics**

All typical values are at  $T_A=25$  °C unless otherwise specified; all other values are at the recommended  $T_A$  and  $T_J$  temperatures. Not production tested.

Currents and	Deveryotar		Condition	T <sub>A</sub> =-4	l Init		
Symbol	Parameter	$v_{DD}(v)$	Condition	Min.	Тур.	Max.	Unit
MIC Switch	· ·					4	
THD	Total Harmonic Distortion	3.8	$R_{T}$ =600 Ω, V <sub>SW</sub> =0.5 V <sub>PP</sub> , f=20 Hz to 20 kHz, V <sub>IN</sub> =2.0 V		0.01		%
O <sub>IRR</sub>	Off Isolation	3.8	f=20 kHz, R <sub>S</sub> =600 Ω, C <sub>L</sub> =0 pF, R <sub>T</sub> =600 Ω		80		dB
Parallel I/O	(Default Timing)					•	
t <sub>ON</sub>	Switch Turn-On Time	3.8	$R_L=10 \text{ k}\Omega, C_L=10 \text{ pF}$		100		μs
t <sub>OFF</sub>	Switch Turn-Off Time	3.8	$R_L=10 \text{ k}\Omega, C_L=10 \text{ pF}$		10		ns
t <sub>DET-IN</sub>	Debounce Time after J_DET Changes from HIGH to LOW	2.7 to 4.5	I <sup>2</sup> C Default Setting		500		ms
t <sub>DET-REM</sub>	Debounce Time after J_DET Changes from Low to HIGH	2.7 to 4.5	I <sup>2</sup> C Default Setting		30		μs
t <sub>DET-MIC</sub>	Detection Time of Audio Jack GND and MIC Terminals	2.7 to 4.5	I <sup>2</sup> C Default Setting		50		ms
t <sub>ESD_DE</sub>	Debounce Time for ESD Event on J_DET (Double-Check J_DET Status)	2.7 to 4.5	I <sup>2</sup> C Default Setting		1		ms
t <sub>POLL</sub>	ON Time of MIC Switch for Sensing SEND/END Key Press in MP3 Mode	2.7 to 4.5	I <sup>2</sup> C Default Setting		15		ms
twait	OFF Time of MIC Switch for Sensing SEND/END Key Press in MP3 Mode	2.7 to 4.5	I <sup>2</sup> C Default Setting		150		ms
t <sub>квк</sub>	Debounce Time for Sensing SEND/END Key Press/Release	2.7 to 4.5	I <sup>2</sup> C Default Setting		45		ms
t <sub>KEY-LONG</sub>	Minimum Time for Long Key Press	2.7 to 4.5	I <sup>2</sup> C Default Setting		900		ms
t <sub>KEY-Double</sub>	Maximum Time between Key Presses for Double-Key Press	2.7 to 4.5	I <sup>2</sup> C Default Setting		1000		ms
t <sub>RES_DE</sub>	Debounce Time for Reset Control	2.7 to 4.5			15		μs
Power Sup	ply Noise Immunity						-
PSRR <sub>sw</sub>	Power Supply Rejection Ratio for Switch	3.8	Power Supply Noise 300 mV <sub>PP</sub> , Measured 10/90%, f=217 Hz		95		dB
PSRRLDO	Power Supply Rejection Ratio for LDO	3.8	Power Supply Noise 300 mV <sub>PP</sub> , Measured 10/90%, f=217 Hz, CEVT=1 LIE		100		dB

## I<sup>2</sup>C Specifications (Fast Mode)

Symbol	Parameter	Min.	Max.	Unit
f <sub>SCL</sub>	SCL Clock Frequency	0	400	kHz
t <sub>HD;STA</sub>	Hold Time (Repeated) START Condition	0.6		μs
t <sub>LOW</sub>	LOW Period of SCL Clock	1.3		μs
t <sub>HIGH</sub>	HIGH Period of SCL Clock	0.6		μs
t <sub>SU;STA</sub>	Set-up Time for Repeated START Condition	0.6		μs
thd;dat	Data Hold Time	0	0.9	μs
t <sub>SU;DAT</sub>	Data Set-up Time <sup>(6)</sup>	100		ns
tr	Rise Time of SDA and SCL Signals <sup>(6,7)</sup>	20+0.1Cb	300	ns
t <sub>f</sub>	Fall Time of SDA and SCL Signals <sup>(6,7)</sup>	20+0.1Cb	300	ns
t <sub>SU;STO</sub>	Set-up Time for STOP Condition	0.6		μs
t <sub>BUF</sub>	BUS-Free Time between STOP and START Conditions	1.3		μs
t <sub>SP</sub>	Pulse Width of Spikes that Must Be Suppressed by the Input Filter	0	50	ns

Notes:

6. A Fast-Mode I<sup>2</sup>C-Bus® device can be used in a Standard-Mode I<sup>2</sup>C-Bus system; but the requirement t<sub>SU;DAT</sub> ≥ 250 ns must be met. This is automatically the case if the device does not stretch the LOW period of the I2C\_SCL signal. If the device does stretch the LOW period of the I2C\_SDA line t<sub>r\_max</sub> + t<sub>SU;DAT</sub> = 1000 + 250 = 1250 ns (according to the Standard-Mode I<sup>2</sup>C Bus specification) before the I2C\_SCL line is released.

7. C<sub>b</sub> equals the total capacitance of one BUS line in pF. If mixed with high-speed devices, faster fall times are allowed according to the I<sup>2</sup>C specification.

#### I<sup>2</sup>C Timing



Figure 5. Definition of Timing for Full-Speed Mode Devices on the I<sup>2</sup>C Bus

Name	Size(Bits)	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Slave Address	8	0	1	0	0	0	1	1	Read/White

Figure 6. I<sup>2</sup>C Slave Address

Table 1.	Register De	finitio	ons									
Address	Register	Туре	Reset Values	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
01H	Device ID	R	00000000		Versi	on ID			Reserved			
02H	Interrupt 1	R	00000000	Res	erved	Send/End Long Key Press	Send/End Double Key Press	Send/End Key Press	Plug Disconnect	4-Pole Plug Connect	3-Pole Plug Connect	
03H	Interrupt 2	R	00000000	Res	erved	Volume Down Long Key release	Volume Down Long Key Press	Volume Down Key Press	Volume Up Long Key release	Volume Up Long Key Press	Volume Up Key Press	
04H	Interrupt Mask 1	R/W	00000000	Res	erved	Send/End Long Key Press Mask	Send/End Double Key Press Mask	Send/End Key Press Mask	Plug Disconnect Mask	4-Pole Plug Connect Mask	3-Pole Plug Connect Mask	
05H	Interrupt Mask 2	R/W	0000000	Res	Reserved		Volume Down Long Key Press Mask	Volume Down Key Press Mask	Volume Up Long Key Release Mask	Volume Up Long Key Press Mask	Volume Up Key Press Mask	
06H	Global Multiplier	R/W	00000100			Global	Multiplier N	lumber				
07H	J_DET Timing	R/W	10000010		Insert	(t <sub>DET-IN</sub> )	Removal (t <sub>DET-REM</sub> ) Global Multiplier Does not apply					
08H	Key Press Timing	R/W	01111000	Doub	le Key Press	Timing (t <sub>KEY</sub>	-Double)	Long Key Press Timing ( $t_{KEY-LONG}$ )				
09H	Music Mode Timing	R/W	00101000	Ke	ey Press Poll	ing Time (t <sub>PO</sub>	ш)	Key	Press Waiti	ng Time (t <sub>v</sub>	<sub>VAIT</sub> )	
0AH	Detection Timing	R/W	01010101	Key Pres	s timing for v down (t	volume up an <sub>Key_Press</sub> )	d volume	[	Detection Tir	ne (t <sub>DET-MIC</sub> )	1	
0BH	Debounce Timing	R/W	10011000	Debounce	e for ESD Ev	rent on J_DE	T (t <sub>ESD_DE</sub> )	Key P	ress Debou	nce Timing	(t <sub>квк</sub> )	
0CH	Control	R/W	01001000	Stuck S/E On/Off	Stuck S/E On/Off All Key as Double Long Key Send/End Key Press Press On/Off On/Off On/Off		Long Key Press On/Off	Music Mode	Jack Det On/Off	3/ 4-Pole Det On/Off	LDO Output On/Off	
0DH	Detection Thresholds	R/W	11101010	Compai	rator 2 (Senc Clos	l/End Key - N sed)	Compara	tor 1 (Send/ Ope	End Key - I en)	Normally		
0EH	Detection Thresholds	R/W	01111001	Comparator 4 (Volume Down) Comparator 3 (Volume Down)					wn)			
0FH	Reset Control	R/W	00000000	Reserved Jack Removal Reset					Global Reset			
10H	Reserved	R/W	Reserved		Reserved							

#### Notes:

Write "0" to undefined register bits. 8.

9. Values read from undefined register bits are not defined and are invalid.
10. Blocks in green color mean setting change is implemented upon next use.

11. Blocks in blue color mean setting change is implemented after jack removal.

#### Table 2. I<sup>2</sup>C Control

Reserved Register bit read out as 0 Address: 01H Reset Value: 00000000 Type: Read

Device ID			Default 0000000		
Bit #	Name	Size	Function		
0:3	Reserved	4	Do Not Use		
4.7	Version ID	4	0000 = Version 0.0		
4.7			0001 = Version 0.1		

#### Table 3. Interrupt 1

Address: 02H

Reset Value: 00000000

Type: Read/Clear

	Interrupt 1		Default 0000000			
Bit #	Name	Size		Function		
0	2 Dele Plug Connect	1	0: No Headset Connected			
0	3-Pole Plug Connect	1	1: 3-Pole Headset Connecte	ed		
1			0: No Headset Connected			
1 4-Pole Plug Connect		1	1: 4-Pole Headset Connecte	ed		
2	Blug Disconnect	1	0: No Update			
2	2 Plug Disconnect		1: Headset Disconnected			
2	Sand/End Koy/ Broos	1	0: Send/End Key Not Press	ed		
3	Send/End Key Fless	1	1: Send/End Key Pressed			
4	Sand/End Double Key Press	1	0: Send/End Double Key No	ot Pressed		
4	4 Send/End Double Key Press		1: Send/End Double Key Pr	essed		
F	Cand/End Long Key Press		0: Send/End Long Key not Pressed			
5	Send/End Long Key Fless		1: Send/End Long Key Pres	sed		
6:7	Reserved	2	Do Not Use			

Table 4. Interrupt 2

Address: 03H

Reset Value: 00000000

Type: Read/Clear

	Interrupt 2		Default	0000000				
Bit #	Name	Size	Fu	Inction				
0	Volume Lin Kov Bross	1	0: Volume Up key not p	ressed				
0	Volume Op Key Fless		1: Volume Up key pressed					
1	Volume Lip Koy Long Pross	1	0: Volume Up Long key not pressed					
I	Volume op Rey Long Fless	I	1: Volume Up Long key	pressed				
2	Volume Lin Koy Long Boloopo	1	0: Volume Up Long key	0: Volume Up Long key not released				
2	Volume op Key Long Release	I	1: Volume Up Long key released					
2	Volumo Down Koy Bross	1	0: Volume Down key not pressed					
3	Volume Down Rey Fless		1: Volume Down Key P	ress				
1	Volumo Down Long Kov Proco	1	0: Volume Down Long I	Key Not Pressed				
4	Volume Down Long Rey Fless	I	1: Volume Down Long	Key Pressed				
5	Volumo Down Long Koy Polooso	1	0: Volume Down Key N	ot Released				
5	Volume Down Long Rey Release	I	1: Volume Down Key R	eleased				
6:7	Reserved	2	Do Not Use					

#### Table 5. Interrupt Mask 1

Address: 04H Reset Value: 00000000 Type: Read/Write

	Interrupt Mask 1		Default	0000000				
Bit #	Name	Size	F	Function				
0	2 Polo Plug Connect	1	0: Do Not Mask 3-Pole Plug Co	onnect Interrupt				
0	S-Fole Flug Connect		1: Mask 3-Pole Plug Connect I	nterrupt				
1	4 Polo Plug Connect	1	0: Do Not Mask 4-Pole Plug Connect Interrupt					
I	4-Fole Flug Connect		1: Mask 4-Pole Plug Connect I	nterrupt				
2	Blug Disconnect	1	0: Do Not Mask Plug Disconne	ct Interrupt				
2	Flug Disconnect		1: Mask Plug Disconnect Intern	upt				
2	Sand/End Kay Proce	1	0: Do Not Mask Send/End Key	Press Interrupt				
3	Selid/Elia Rey Fless		1: Mask Send/End Key Press I	nterrupt				
4	Sand/End Dauble Key Press	1	0: Do Not Mask Send/End Key	Double Press Interrupt				
4	Send/End Double Rey Fless		1: Mask Send/End Key Double	Key Press Interrupt				
F	Sand/End Lang Kay Drass	1	0: Do Not Mask Send/End Lon	g Key Press Interrupt				
5 Send/End Long Key Fless			1: Mask Send/End Long Key Press Interrupt					
6:7	Reserved	2	Do Not Use					

#### Table 6. Interrupt Mask 2

Address: 05H Reset Value: 00000000

Type: Read/Write

		Interrupt Mask 2		Default 0000000						
Bit #		Name	Size			Functio	n			
0	Val	ima Lin Kay Braaa	1	0: Do Not	Ma	ask Volume Up Key Pre	ss Interrupt			
0	1: Mask Volume Up Key Press Interrupt									
1	Volum	0: Do Not Mask Volume Up Long Key Press Interrupt								
	Volume	e op key Long Pless	I	1: Mask \	/ol	ume Up Long Key Pres	s Interrupt			
2	Volumo	Lin Koy Long Pologoo	1	0: Do Not	Ma	ask Volume Up Long Ke	ey Release Interrupt			
2	volume	Op Key Long Kelease		1: Mask V	οlι	ume Up Long Key Rele	ase Interrupt			
2	Volum	no Down Koy Broop	1	0: Do Not Mask Volume Down Key Press Interrupt						
5	Volui	ne Down Rey Fless		1: Mask V	οlι	ume Down Key Press In	terrupt			
4	Volumo	Down Long Koy Broop	1	0: Do Not	Ma	ask Volume Down Long	Key Press Interrupt			
4	volume	Down Long Key Fless	1	1: Mask V	οlι	ume Down Long Key Pr	ess Interrupt			
F	Volumo D	own Long Koy Bologoo	1	0: Do Not Mask Volume Down key Release Interrupt						
5	Volume L	Jown Long Key Kelease		1: Mask Volume Down key released Interrupt						
6:7		Reserved	2	2 Do Not Use						

#### Table 7. Global Multiplier Number

Address: 06H Reset Value: 00000100 Type: Read/Write

		Default	00000100								
Bit 7	Bit 6	Bit 5	Bit 4	Bit 1	Bit 0	Function					
	Reserved 0 0 0										
	Reserved 0 0 1										
		Reserved			0	1	0	1/4			
		Reserved			0	1	1		1/2		
		Reserved			1	0	0		1		
		Reserved			1	0	1		2		
		Reserved		1	1	0		4			
	Reserved 1 1 1										

#### Table 8. J\_DET Timing

Address: 07H Reset Value: 10000010 Type: Read/Write

		Default	10000010									
		Insert (t	det_in)			Rem	oval (t <sub>DE</sub>	т_REM <b>) (G</b>	lobal Mu	Itiplier Does	Not Apply)	
Bit 7	Bit 6	Bit 5	Bit 4	Fund	ction	Bit 3 Bit 2 Bit 1 Bit 0				Function		
0	0	0	0	100		0	0	0	0	10		
0	0	0	1	150		0	0	0	1	20		
0	0	1	0	200		0	0	1	0	30		
0	0	1	1	250		0	0	1	1	40		
0	1	0	0	300		0	1	0	0	50		
0	1	0	1	350		0	1	0	1	60		
0	1	1	0	400		0	1	1	0	70		
0	1	1	1	450		0	1	1	1	80	1	
1	0	0	0	500	ms	1	0	0	0	90	μs	
1	0	0	1	550		1	0	0	1	100		
1	0	1	0	600		1	0	1	0	110		
1	0	1	1	650		1	0	1	1	120		
1	1	0	0	700		1	1	0	0	130		
1	1	0	1	750		1	1	0	1	140	]	
1	1	1	0	800		1	1	1	0	140		
1	1	1	1	850	]	1	1	1	1	140		

#### Table 9. Key Press Timing

Address: 08H Reset Value: 01111000 Type: Read/Write

				Default	00101000						
	Doubl	e Key Pı	ress (t <sub>DO</sub>	UBLE)				Lon	g Key Pr	ess (t <sub>LONG</sub> )	
Bit 7	Bit 6	Bit 5	Bit 4	Fund	ction	Bit 3	Bit 2	Bit 1	Bit 0	Fur	nction
0	0	0	0	100		0	0	0	0	500	
0	0	0	1	200		0	0	0	1	550	-
0	0	1	0	300		0	0	1	0	600	-
0	0	1	1	400		0	0	1	1	650	
0	1	0	0	500		0	1	0	0	700	
0	1	0	1	600		0	1	0	1	750	
0	1	1	0	800		0	1	1	0	800	
0	1	1	1	1000		0	1	1	1	850	ma
1	0	0	0	1100	1115	1	0	0	0	900	1115
1	0	0	1	1200		1	0	0	1	1000	
1	0	1	0	1300		1	0	1	0	1100	
1	0	1	1	1400		1	0	1	1	1200	
1	1	0	0	1500		1	1	0	0	1300	
1	1	0	1	1600	]	1	1	0	1	1400	
1	1	1	0	1800		1	1	1	0	1500	
1	1	1	1	2000		1	1	1	1	2000	

#### Table 10. Music Mode Timing

Address: 09H Reset Value: 01011000 Type: Read/Write

			Default	01011000							
	Key P	ress Po	lling Tin	ne (t <sub>POL</sub>	L)		ł	Key Pres	s Waitii	n <mark>g Time (t<sub>wait</sub></mark>	)
Bit 7	Bit 6	Bit 5	Bit 4	Fu	unction	Bit 3	Bit 2	Bit 1	Bit 0	Fur	oction
0	0	0	0	5		0	0	0	0	5	
0	0	0	1	10		0	0	0	1	10	
0	0	1	0	15		0	0	1	0	15	
0	0	1	1	20		0	0	1	1	20	
0	1	0	0	25		0	1	0	0	25	
0	1	0	1	30		0	1	0	1	30	
0	1	1	0	35		0	1	1	0	50	
0	1	1	1	40		0	1	1	1	100	me
1	0	0	0	45	1115	1	0	0	0	150	1115
1	0	0	1	50		1	0	0	1	200	
1	0	1	0	60		1	0	1	0	250	
1	0	1	1	70		1	0	1	1	300	
1	1	0	0	80		1	1	0	0	350	
1	1	0	1	90		1	1	0	1	400	
1	1	1	0	100		1	1	1	0	450	
1	1	1	1	150		1	1	1	1	500	

#### Table 11. Detection Timing

Address: 0AH Reset Value: 01010101 Type: Read/Write

			Dete	ction Timin	g					Default	01010101	
Key Pre	ss Timing	g for Volu	ume Up and	d Volume D	Oown (t <sub>KEY</sub> )			Detect	ion T	ime (t <sub>DET_M</sub>	lc)	
Bit 7	Bit 6	Bit 5	Bit 4	Fund	ction	Bit 3	Bit 2	Bit 1	Bit	0 Function		
0	0	0	0	50		0	0	0	0	5		
0	0	0	1	100		0	0	0	1	10		
0	0	1	0	150		0	0	1	0	15		
0	0	1	1	200		0	0	1	1	20		
0	1	0	0	250		0	1	0	0	25		
0	1	0	1	300		0	1	0	1	50		
0	1	1	0	350		0	1	1	0	75		
0	1	1	1	400	me	0	1	1	1	100	me	
1	0	0	0	450	1115	1	0	0	0	150	1115	
1	0	0	1	500		1	0	0	1	200		
1	0	1	0	550		1	0	1	0	250		
1	0	1	1	600		1	0	1	1	300		
1	1	0	0	650		1	1	0	0	350		
1	1	0	1	700		1	1	0	1	400		
1	1	1	0	750		1	1	1	0	450		
1	1	1	1	800		1	1	1	1	500		

#### Table 12. Key Press Debounce Timing

Address: 0BH Reset Value: 10011000 Type: Read/Write

			Key Pre	ess Deb	ounce	Timing				Default	10011000	
Debou (G	unce Tim Blobal Mu	ning for l ultiplier	ESD Eve Does No	nt on J ot Apply	_DET ′)	Key Press Debounce Timing						
Bit 7	Bit 6	Bit 5	Bit 4	Func	ction	Bit 3	Bit 2	Bit 1	Bit 0	Fun	ction	
0	0	0	0	100		0	0	0	0	5		
0	0	0	1	200		0	0	0	1	10		
0	0	1	0	300		0	0	1	0	15		
0	0	1	1	400		0	0	1	1	20		
0	1	0	0	500		0	1	0	0	25		
0	1	0	1	600		0	1	0	1	30		
0	1	1	0	700		0	1	1	0	35		
0	1	1	1	800	1	0	1	1	1	40		
1	0	0	0	900	μs	1	0	0	0	45	ms	
1	0	0	1	1000		1	0	0	1	50		
1	0	1	0	1200		1	0	1	0	55		
1	0	1	1	1400		1	0	1	1	60		
1	1	0	0	1600	]	1	1	0	0	65		
1	1	0	1	1800	]	1	1	0	1	70		
1	1	1	0	2000	]	1	1	1	0	75		
1	1	1	1	5000		1	1	1	1	80		

#### Table 13. Control 1

Address: 0CH Reset Value: 01001000 Type: Read/Write

	Control 1		Default	01001000				
Bit #	Name	Size	Function	on				
0		1	0: LDO Output On					
0			1: LDO Output Off					
1	MIC Detection	1	0: MIC Detection On					
1		I	1: MIC Detection Off					
0	lack detection	1	0: Jack Detection On					
2		I	1: Jack Detection Off					
2	Music Mode	1	0: Music Mode On					
3		I	1: Music Mode Off					
4	Long Koy Pross Eulection	1	0: Long Key Press Function On					
4	Long Rey Fless Function	I	1: Long Key Press Function Off					
Б	Double Key Press Eulection	1	0: Double Key Press Function Or	1				
5	Double Rey Fless Function	I	1: Double Key Press Function Of	f				
6	All Koy as Sand/End Eurotian	1	0: All Key as Send/End Function	On				
0	All Rey as Send/End Function	I	1: All Key as Send/End Function	Off				
7	Stuck S/E Eurotion	1	0: Stuck Send/End Function On					
/	Sluck S/E FUNCTION	1	1: Stuck Send/End Function OFF					

#### Table 14. Detection Thresholds 1

Address: 0DH

Reset Value: 11101010

#### Type: Read/Write

		Default	11101010									
	Norm	nally Clo	sed S/E	Key		Normal	ly Open	S/E Key	Maximur	num/Volume up Key Minimum		
Bit 7	Bit 6	Bit 5	Bit 4	Fund	tion	Bit 3	Bit 2	Bit 1	Bit 0	Fu	nction	
0	0	0	0	1000		0	0	0	0	20		
0	0	0	1	1100		0	0	0	1	30		
0	0	1	0	1200		0	0	1	0	40		
0	0	1	1	1300		0	0	1	1	50		
0	1	0	0	1400		0	1	0	0	60		
0	1	0	1	1500		0	1	0	1	70		
0	1	1	0	1600		0	1	1	0	80		
0	1	1	1	1650	mV	0	1	1	1	90	\/	
1	0	0	0	1700		1	0	0	0	100	iiiv	
1	0	0	1	1750		1	0	0	1	110		
1	0	1	0	1800		1	0	1	0	120		
1	0	1	1	1900		1	0	1	1	130		
1	1	0	0	2000		1	1	0	0	140		
1	1	0	1	2200	]	1	1	0	1	150		
1	1	1	0	2300		1	1	1	0	160		
1	1	1	1	2400		1	1	1	1	170	]	

#### Table 15. Detection Thresholds 2

Address: 0EH Reset Value: 01110111 Type: Read/Write

			Default	01111001								
	Volum	e Down I	Key Max	imum		Volun	ne Up Ke	ey Maxin	num/Volu	lume Down Key Minimum		
Bit 7	Bit 6	Bit 5	Bit 4	Func	tion	Bit 3 Bit 2 Bit 1 Bit 0				Function		
0	0	0	0	270		0	0	0	0	110		
0	0	0	1	330		0	0	0	1	125		
0	0	1	0	390		0	0	1	0	145		
0	0	1	1	450		0	0	1	1	160		
0	1	0	0	510		0	1	0	0	175		
0	1	0	1	570		0	1	0	1	190		
0	1	1	0	630		0	1	1	0	205		
0	1	1	1	690	m\/	0	1	1	1	220	m\/	
1	0	0	0	750		1	0	0	0	235	iiiv	
1	0	0	1	810		1	0	0	1	250		
1	0	1	0	870		1	0	1	0	265		
1	0	1	1	930		1	0	1	1	280		
1	1	0	0	990		1	1	0	0	295		
1	1	0	1	1050		1	1	0	1	310		
1	1	1	0	1120		1	1	1	0	325		
1	1	1	1	1190		1	1	1	1	340		

#### Table 16. Reset Control

Address: 0FH Reset Value: 0000000 Type: Read/Write

	Reset Control		Default	0000000
Bit #	Name	Size	Function	
	Global Reset	1	0: No Change	
0			1: Reset Device Reset to all I2C ir (timing, comparator threshold)	nto default values
1	Jack Removal Reset	1	0: No Change	
			1: Clear I2C register related to Jack Removal process (interrupt)	
2:7	Reserved	5	Do Not Use	

#### **Nominal Values**

Bump Pitch	Overall Package Height	Silicon Thickness	Solder Bump Height	Solder Bump Diameter
0.4 mm	0.586 mm	0.378 mm	0.208 mm	0.260 mm

#### Package Specific Dimensions

D	E	Х	Y
1.56 mm	1.16 mm	0.18 mm	0.18 mm

	REVISIONS				
REV	DESCRIPTION	DATE	APP'D / SITE		
1	Initial drawing release.	8-19-09	L. England / FSME		





#### RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

## F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. DRAWING FILENAME: MKT-UC012ACrev1.

APPROVALS	DATE					
L. England	8-19-09	SEMICC				
DFTG. CHK. S. Martin	8-19-09					
ENGR. CHK.						
			.4101101	1 11011, 2		
PROJECTIO	N	SCALE	SIZE	DRAWING NUMBER		REV
		N/A	N/A	MKT-l	JC012AC	1
INCH INAL			SCALET	RAWING	SHEET 1 of	1

BOTTOM VIEW

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